TOSHIBA BIPOLAR DIGITAL INTEGRATED CIRCUIT SILICON MONOLITHIC

TD62318AP,TD62318AF

4CH LOW INPUT ACTIVE HIGH-CURRENT DARLINGTON SINK DRIVER

The TD62318AP and TD62318AF are non-inverting transistor arrays which are comprised of four NPN darlington output stages and PNP input stages.

These devices can be operated by source input voltage and are suitable for operation with a 5–V general pourposed logic IC such as TTL, 5–V CMOS and 5–V Microprocessor which have sink current output drivers.

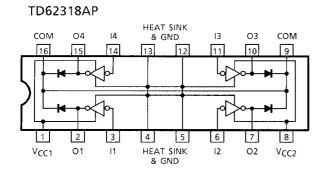
Applications include relay, hammer, lamp and stepping moter drivers.

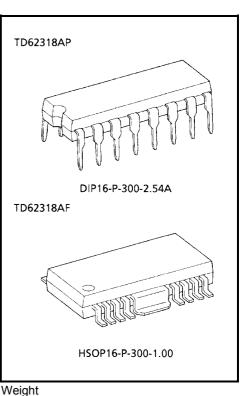
Please observe the thermal condition for using.

FEATURES

- Output current (single output) 700 mA (Max)
- High sustaining voltage output 50 V (Min)
- Output clamp diodes
- Input compatible with TTL and 5-V CMOS
- Low level active inputs
- Standard supply voltage
- Two VCC terminals VCC1, VCC2 (separated)
- GND and SUB terminal = heat sink
- Package type-AP: DIP-16 pin
- Package type-AF: HSOP-16 pin

PIN CONNECTION (TOP VIEW)

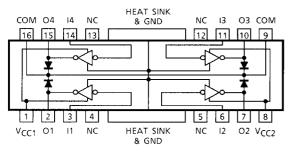


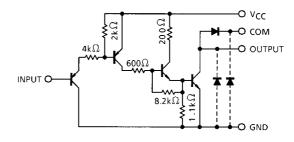


DIP16-P-300-2.54A : 1.11 g (Typ.) HSOP16-P-300-1.00: 0.50 g (Typ.)

SCHEMATICS (EACH DRIVER)

TD62318AF





Note: The input and output parasitic diodes cannot be used as clamp diodes.

MAXIMUM RATINGS (Ta = 25°C)

CHARACTERISTICS		SYMBOL	RATING	UNIT	
Supply Voltage		V _{CC}	-0.5~17	V	
Output Sustaining Voltage	V _{CE (SUS)}	-0.5~50	V		
Output Current		I _{OUT}	700	mA / ch	
Input Current		I _{IN}	-10	mA	
Input Voltage		V _{IN}	-0.5~30	V	
Clamp Diode Reverse Voltage		V _R	50	V	
Clamp Diode Forward Current		١ _F	700	mA	
Power Dissipation	AP	D-	1.47 / 2.7 (Note 1)	W	
	AF	P _D	0.9 / 1.4 (Note 2)	vv	
Operating Temperature		T _{opr}	-40~85	°C	
Storage Temperature		T _{stg}	-55~150	°C	

Note 1: On Glass Epoxy PCB (50 × 50 × 1.6 mm Cu 50%)

Note 2: On Glass Epoxy PCB (60 × 30 × 1.6 mm Cu 30%)

RECOMMENDED OPERATING CONDITIONS (Ta = -40~85°C)

CHARACTERISTIC		SYMBOL	CONDITION		MIN	TYP.	MAX	UNIT	
Supply Voltage		V _{CC}			4.5	_	5.5	V	
Output Sustaining Voltage		V _{CE (SUS)}			0	_	50	V	
			DC 1 circuit, Ta = 25 °C		0	_	570		
	AP	Ιουτ	T _{pw} = 25ms 4 circuits Ta = 85°C T _j = 120°C	Duty = 10%	0	_	570	mA / ch	
Output Current				Duty = 50%	0	_	570		
	AF			Duty = 10%	0	_	570		
				Duty = 50%	0	—	480		
Input Voltage		V _{IN}			0	_	15	V	
Input Voltage	Output On	V _{IN (ON)}			0	_	V _{CC} −3.6	v	
	Output Off	V _{IN (OFF)}			V _{CC} -1.6	_	5.5		
Clamp Diode Reverse Voltage		V _R				_	50	V	
Clamp Diode Forward Current		١ _F			_	_	500	mA	
Power Dissipation	AP	PD	Ta = 85°C	(Note 1)	_	—	1.4	w	
	AF		Ta = 85°C	(Note 2)	_	_	0.7	vv	

 Note 1:
 On Glass Epoxy PCB (50 × 50 × 1.6 mm Cu 50%)

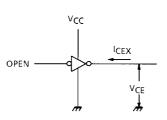
 Note 2:
 On Glass Epoxy PCB 60 × 30 × 1.6 mm Cu 30%)

ELECTRICAL CHARACTERISTICS (Ta = 25°C)

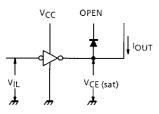
CHARACTERISTIC		SYMBOL	TEST CIR- CUIT	TEST CONDITION	MIN	TYP.	MAX	UNIT
Input Voltage	"H" Level	VIH			V _{CC} −1.6	_	25	v
	"L" Level	VIL			0	_	V _{CC} -3.6	
Input Current	"H" Level	IIН	2		_	_	10	μA
	"L" Level	١ _{١L}			_	-0.05	-0.36	mA
Output Leakage Current			1	V _{CE} = 50 V, Ta = 25°C	_	_	50	μA
		ICEX		V _{CE} = 50 V, Ta = 85°C	_	_	100	
Output Saturation Voltage		V _{CE (sat)}	3	I _{OUT} = 0.5 A, V _{CC} = 4.5 V	_	-	0.8	V
				I _{OUT} = 0.2 A, V _{CC} = 4.5 V	_	-	0.45	
Clamp Diode Reverse Current		I _R	4	V _R = 50 V, Ta = 25°C	—	_	50	μA
				V _R = 50 V, Ta = 85°C	—	_	100	
Clamp Diode Forward Voltage		VF	5	I _F = 500 mA	—	_	2.0	V
Supply Current	Output On	I _{CC (ON)}	2	V_{CC} = 5.5 V, V_{IN} = 0 V	_	35	40	mA / ch
	Output Off	I _{CC} (OFF)	2	V_{CC} = 5.5 V, V_{IN} = V_{CC}	_	_	10	μA
Turn-On Delay		t _{ON}	- 6	V _{OUT} = 50 V, R _L = 90 Ω V _{CC} = 5.0 V, C _L = 15 pF	_	0.4	0.8	μs
Turn−Off Delay		tOFF			_	8.0	16.0	

TEST CIRCUIT

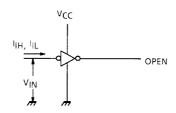
1. ICEX



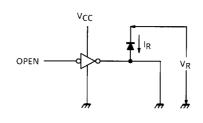
3. V_{CE (sat)}





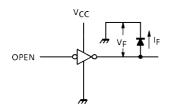


4. I _R

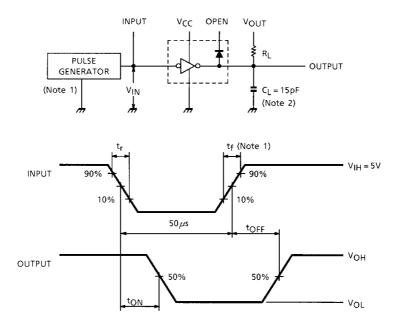


5. V_F

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6. t_{ON}, t_{OFF}



- Note 1: Pulse Width 50 μ s, duty cycle 10% Output impedance 50 Ω , t_r ≤ 5 ns, t_f ≤ 10 ns
- Note 2: C_L includes probe and jig capacitance.

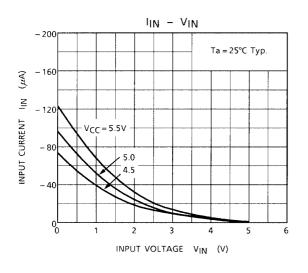
PRECAUTIONS for USING

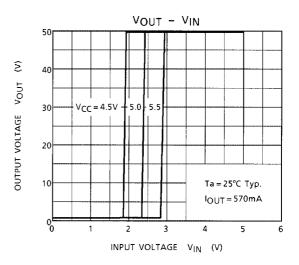
This IC does not include built-in protection circuits for excess current or overvoltage.

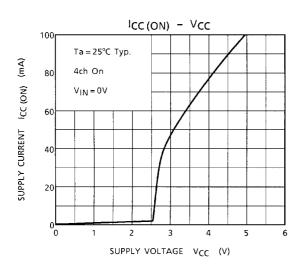
If this IC is subjected to excess current or overvoltage, it may be destroyed.

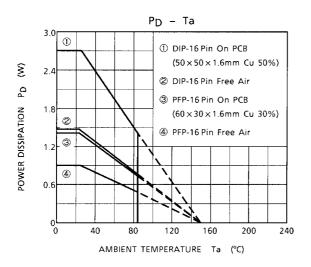
Hence, the utmost care must be taken when systems which incorporate this IC are designed.

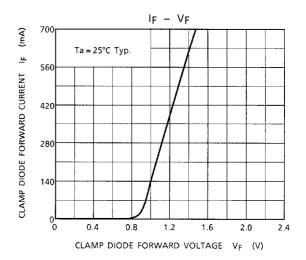
Utmost care is necessary in the design of the output line, V_{CC} , COMMON and GND line since IC may be destroyed due to short-circuit between outputs, air contamination fault, or fault by improper grounding.

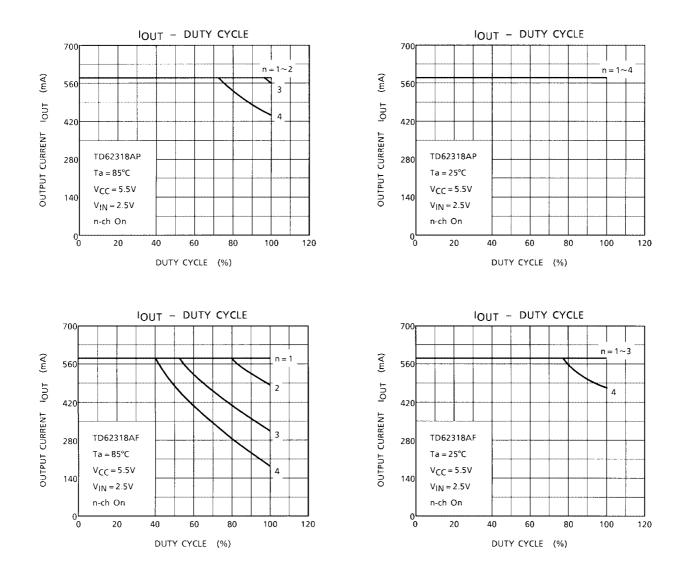








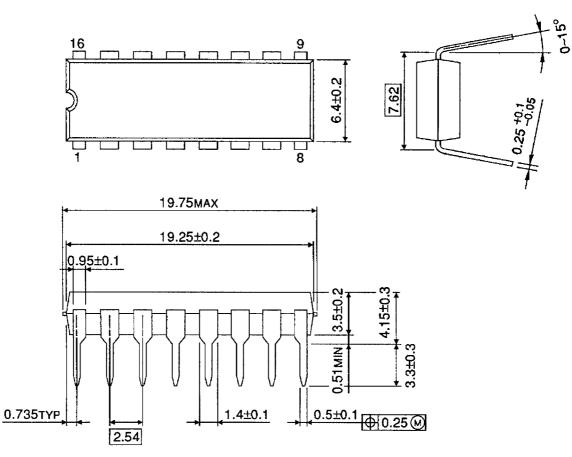




PACKAGE DIMENSIONS

DIP16-P-300-2.54A

Unit: mm

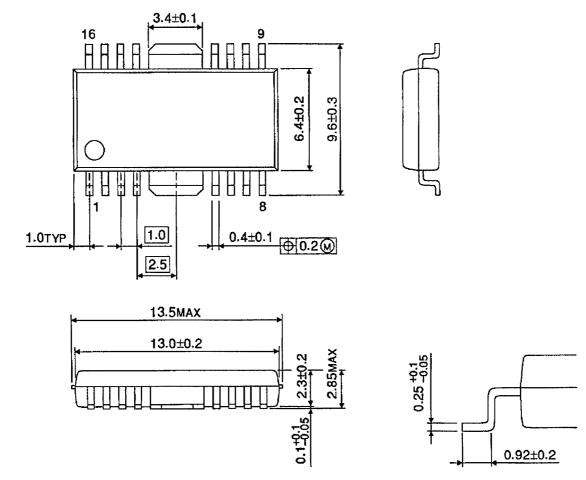


Weight: 1.11 g (Typ.)

PACKAGE DIMENSIONS

HSOP16-P-300-1.00

Unit: mm



Weight: 0.50 g (Typ.)

RESTRICTIONS ON PRODUCT USE

000707EBA

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